

**IN THE CLAIMS:**

Please cancel claims 2-18 without prejudice or disclaimer to the subject matter recited therein.

Please amend the following claim:

1. (Amended) A semiconductor device, comprising:

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a semiconductor substrate having a circuit forming surface, and having a plurality of electrode pads provided on the circuit forming surface, said electrode pads being disposed to surround an area of the circuit forming surface;

ay  
a semiconductor element mounted within the area of the circuit forming surface; reference lines that include an adhesive, said reference lines being disposed under the semiconductor element, and being respectively provided at positions corresponding to at least three corners of the semiconductor element, said reference lines being adapted for use as a reference for determining a correct placement of the semiconductor element within the area of the circuit forming surface; and

a sealing resin that seals said semiconductor element.

Please add the following claim:

--19. A method of mounting a semiconductor element on a substrate, comprising:

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providing a semiconductor substrate having a circuit forming surface, and having a plurality of electrode pads provided on the circuit forming surface, the electrode pads being disposed to surround an area of the circuit forming surface;

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providing a semiconductor element having at least three corners;

forming reference lines that include an adhesive on the semiconductor substrate, the reference lines being respectively provided at positions corresponding to the at least three corners of the semiconductor element;

AS positioning the semiconductor element in the area of the circuit forming surface while using the reference lines to determine a correct placement of the semiconductor element within the area of the circuit forming surface;

adhering the semiconductor element to the semiconductor substrate using the adhesive of the reference lines; and

sealing said semiconductor element with a sealing resin.--

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### **REMARKS**

The Examiner's Action mailed on June 18, 2002 has been received and its contents carefully considered.

In this Amendment, Applicant has editorially amended the specification, canceled claims 2-18, amended claim 1 to include the subject matter of dependent claim 3, and added claim 19. Further Figures 9b, 10a and 10b have been amended. Claims 1 and 19 are the independent claims. Claims 1 and 19 are the only claims pending in the application. For at least the following reasons, it is submitted that this application is in condition for allowance.

The Examiner has objected to Figures 10a and 10b for not being labeled as prior art. Further, the drawings have been objected to because Figure 9b includes the reference character 706a, which was not described in the specification. Moreover, the